PZTA92T1

Preferred Devices

High Voltage Transistor

PNP Silicon

Features

• Pb-Free Package is Available

MAXIMUM RATINGS (T_C = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V _{CEO}	-300	Vdc
Collector-Base Voltage	V _{CBO}	-300	Vdc
Emitter-Base Voltage	V _{EBO}	-5.0	Vdc
Collector Current	I _C	-50	mAdc
Total Power Dissipation up to @ T _A = 25°C (Note 1)	P _D	1.5	W
Storage Temperature Range	T _{stg}	-65 to 150	°C
Junction Temperature	TJ	150	°C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	83.3	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

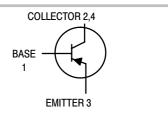
1. Device mounted on a FR-4 glass epoxy printed circuit board 1.575 in x 1.575 in x 0.0625 in; mounting pad for the collector lead = 0.93 sq in.



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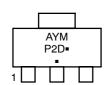
SOT-223 PACKAGE PNP SILICON HIGH VOLTAGE TRANSISTOR SURFACE MOUNT





SOT-223 CASE 318E-04 STYLE 1





P2D = Specific Device Code A = Assembly Location

Y = Year
M = Date Code
Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

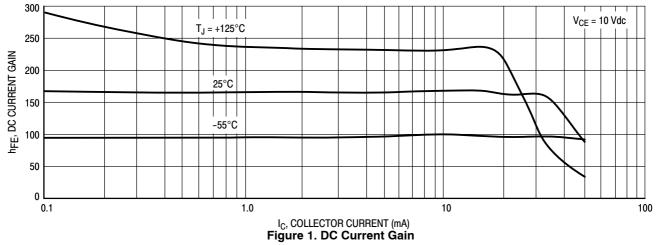
Preferred devices are recommended choices for future use and best overall value.

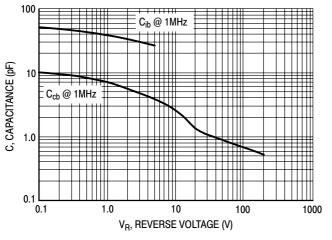
PZTA92T1

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristics	Symbol	Min	Max	Unit
OFF CHARACTERISTICS	•	•	•	
Collector-Emitter Breakdown Voltage (Note 2) $(I_C = -1.0 \text{ mAdc}, I_B = 0)$	V _{(BR)CEO}	-300	_	Vdc
Collector-Base Breakdown Voltage ($I_C = -100 \mu Adc, I_E = 0$)	V _{(BR)CBO}	-300	_	Vdc
Emitter-Base Breakdown Voltage ($I_E = -100 \mu Adc$, $I_C = 0$)	V _{(BR)EBO}	-5.0	_	Vdc
Collector-Base Cutoff Current $(V_{CB} = -200 \text{ Vdc}, I_E = 0)$	I _{CBO}	_	-0.25	μAdc
Emitter-Base Cutoff Current $(V_{BE} = -3.0 \text{ Vdc}, I_C = 0)$	I _{EBO}	_	-0.1	μAdc
ON CHARACTERISTICS	<u>.</u>			
DC Current Gain	h _{FE}	25 40 40	_ _ _	_
Saturation Voltages $ \begin{array}{l} \text{(I}_{C} = -20 \text{ mAdc, I}_{B} = -2.0 \text{ mAdc)} \\ \text{(I}_{C} = -20 \text{ mAdc, I}_{B} = -2.0 \text{ mAdc)} \end{array} $	V _{CE} (sat) V _{BE} (sat)	_	-0.5 -0.9	Vdc
DYNAMIC CHARACTERISTICS				
Collector-Base Capacitance @ f = 1.0 MHz (V _{CB} = -20 Vdc, I _E = 0)	C _{cb}	_	6.0	pF
Current-Gain — Bandwidth Product (I _C = -10 mAdc, V _{CE} = -20 Vdc, f = 100 MHz)	f _T	50	_	MHz

^{2.} Pulse Test Conditions, t_p = 300 μ s, δ 0.02.





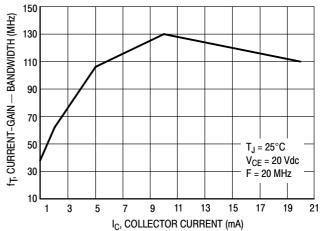
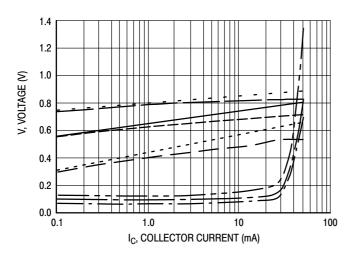


Figure 2. Capacitance

Figure 3. Current-Gain — Bandwidth



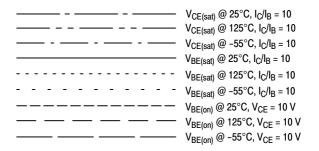


Figure 4. "ON" Voltages

ORDERING INFORMATION

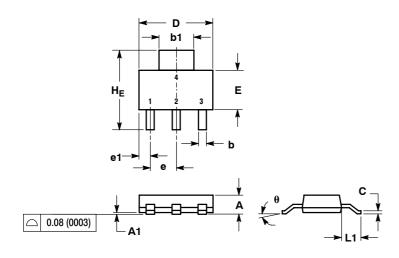
Device	Package	Shipping †
PZTA92T1	SOT-223	1000 / Tape & Reel
PZTA92T1G	SOT-223 (Pb-Free)	1000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PZTA92T1

PACKAGE DIMENSIONS

SOT-223 (TO-261) CASE 318E-04 ISSUE L



NOTES

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.50	1.63	1.75	0.060	0.064	0.068
A1	0.02	0.06	0.10	0.001	0.002	0.004
b	0.60	0.75	0.89	0.024	0.030	0.035
b1	2.90	3.06	3.20	0.115	0.121	0.126
С	0.24	0.29	0.35	0.009	0.012	0.014
D	6.30	6.50	6.70	0.249	0.256	0.263
E	3.30	3.50	3.70	0.130	0.138	0.145
е	2.20	2.30	2.40	0.087	0.091	0.094
e1	0.85	0.94	1.05	0.033	0.037	0.041
L1	1.50	1.75	2.00	0.060	0.069	0.078
HE	6.70	7.00	7.30	0.264	0.276	0.287
θ	0°	-	10°	0°	-	10°

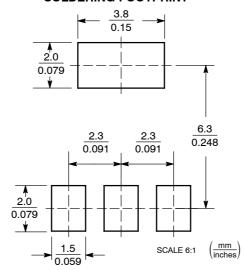
STYLE 1:

PIN 1. BASE

COLLECTOR
 FMITTER

4. COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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